



SPECIFICATIONS					
:	PTC				
:	SH240320T062-LAA07				
:	PH240320T062-LAA07				
:	01				
:	003				
:	JLMD- PH240320T062-LAA07_001				
:	JPKG- PH240320T062-LAA07_002				
	:				

# **Customer Approved**

Date:

Approved	Checked	Designer
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Preliminary specification for design input

Specification for sample approval

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# History of Version

Date	Ver.	Edi.	Description	Page	Design by
07/25/2017	01	001	Sample Specification	-	張佑雨
10/16/2017	01	002	Modify Color of CIE Coordinate	6	張佑雨
07/03/2017	01	003	Modify LCM Packaging	Appendix	夏子豪

Total: 28 Pages



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## **1. SPECIFICATIONS**

## 1.1 Features

#### Main LCD Panel

Item	Standard Value				
Display Type	240 * (R 、 G 、 B) * 320 Dots				
LCD Type	a-Si TFT , Positive, Transmissive				
Screen size(inch)	2.4" (Diagonal)				
Other(controller / driver IC)	ST7789VI				
Viewing Direction	12 O'clock				
Color configuration	R.G.B. vertical stripe				
Interface	8080-8 &16 Bits data bus				
	THIS PRODUCT CONFORMS THE ROHS OF PTC				
ROHS	Detail information please refer web site :				
	http://www.powertip.com.tw/news.php?area_id_view=1085560481/				

# **1.2 Mechanical Specifications**

Item	Standard Value	Unit
Outline Dimension	42.72 (W) * 61.46 (L) *2.55(H)	mm

#### LCD Panel & Touch Panel

Item	Standard Value		
Viewing Area(LCD)	37.72(W) *49.96(L)	mm	
Active Area(LCD)	36.72(W) * 48.96(L)	mm	

Note : For detailed information please refer to LCM drawing.



## **1.3 Absolute Maximum Ratings**

#### Module

Item	Symbol Condition		Min.	Max.	Unit
	VDD2	-	-0.3	+4.6	V
System Dower Supply Voltage	IOVDD	-	-0.3	+4.6	V
System Power Supply Voltage	VGH	-	+13	+17	V
	VGL	-	-12	-7	
Input Voltage	VIN	-	0.5	IOVDD +0.5	V
Operating Temperature	TOP	-	-30	+80	°C
Storage Temperature	TST	-	-40	+85	°C
Storage Humidity	HD	Ta < 60 °C		90	%RH

## **1.4 DC Electrical Characteristics**

#### Module

GND = 0V, Ta = 25°C

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
System Voltage	VDD2	-	2.4	2.75	3.3	V
Interface Operation Voltage	IOVDD	-	1.65	1.8	3.3	V
Input High Voltage	VIH	-	0.8* IOVDD	-	IOVDD	V
Input Low Voltage	VIL	-	VSS	-	0.2* IOVDD	V
Output High Voltage	VOH	IOH=-1.0mA	0.8* IOVDD	-	IOVDD	V
Output Low Voltage	VOL	IOL=+1.0mA	VSS	-	0.2* IOVDD	V
Supply Current	IDD*1	VDD2=IOVDD=2.8V	-	7	11	mA

Note1 : IDD contains the current of the VDD2 and IOVDD .



#### 1.5 Optical Characteristics TFT LCD Panel

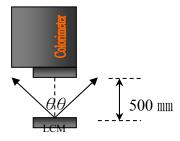
VDD2= 2.8V, Ta=25°C

				- )				
Item		Symbol	Condition	Min.	Тур.	Max.	unit	
Response tin	Response time		-	-	27	41	ms	Note2
	Rear	θY+		-	60	-		
Viewing angle	Front	θY-	CR ≥ 10	-	60	-	Deg.	Note4
	Left	θХ-		-	60	1	Dey.	NOLE4
	Right	θΧ+		-	60	-		
Contrast rati	0	CR	-	500	600	-		Note3
	\A/bita	Х		0.24	0.29	0.34		
	White	Y		0.26	0.31	0.36	-	
	Ded	Х		0.54	0.59	0.64		
Color of CIE Coordinate	Red	Y	IF=80 mA	0.29	0.34	0.39		Note1
Coordinate	Creen	Х	IF-00 IIIA	0.29	0.34	0.39	-	NOLEI
	Green	Y		0.55	0.60	0.65		
	Dhia	Х		0.10	0.15	0.20		
	Blue	Y		0.01	0.06	0.11		
Average Brightr Pattern=white di		IV	IF=80 mA	120	160	-	cd/m2	Note1
Uniformity		∆B	IF= 80 mA	80	-	-	%	Note1

Note1:

- $1 : \triangle B = B(min) / B(max) \times 100\%.$
- 2 : Measurement Condition for Optical Characteristics:
  - a : Environment: 25°C ±5°C / 60±20%R.H, no wind, dark room below 10 Lux at typical lamp current and typical operating frequency.
  - b : Measurement Distance: 500 ± 50 mm, ( $\theta$ = 0°).
  - c : Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.
  - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%.





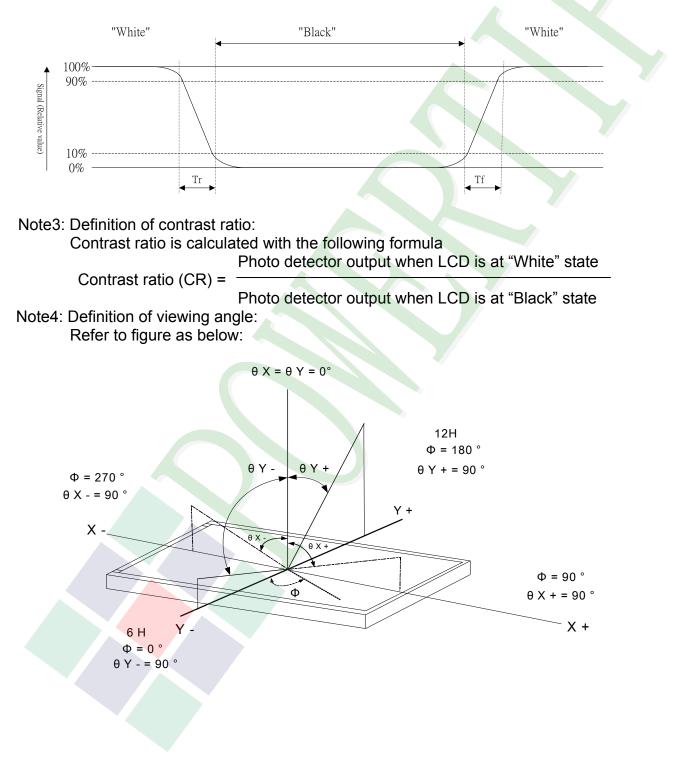
Colorimeter=BM-7 fast



#### Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:





# **1.6 Backlight Characteristics**

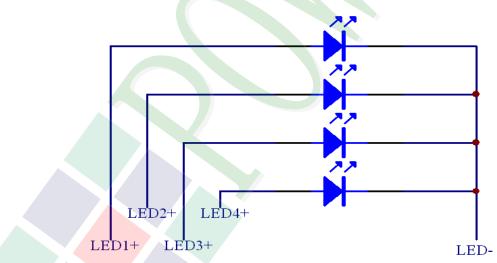
## Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	<b>Ta =25</b> ℃	-	120	mA
Forward Voltage	VF	<b>Ta =25</b> ℃	-	3.6	V
Reverse Voltage	VR	Ta =25℃	-	5.0	V
Power Dissipation	PD	<b>Ta =25</b> ℃	-	360	mW

#### **Electrical / Optical Characteristics**

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Forward Voltage	VF	IF= 80mA	2.8	3.2	3.6	V	
Average Brightness	IV	IF= 80mA	3800	4200	-	cd/m <sup>2</sup>	
Color of CIE Coordinate	Х	IF= 80mA	0.25	0.28	0.31		
	Y	IF- OUTIA	0.25	0.28	0.31	-	
Color			White				
Internal Circuit Diagram							

Internal Circuit Diagram :



#### Other Description

Item	Conditions	Description
Life Time	Ta =25℃	20000 hrs
Life fille	IF= 80 mA	20000 1115



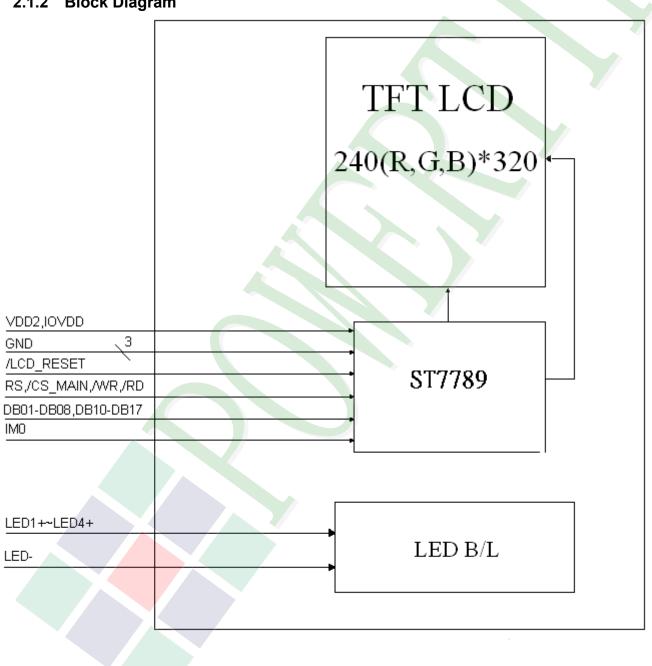
# 2. MODULE STRUCTURE

#### 2.1 Counter Drawing

#### 2.1.1 LCM Mechanical Diagram

\* See Appendix

#### 2.1.2 Block Diagram





# 2.2 Interface Pin Description

Pin No	Symbol	Function
1	GND	System Ground.
2	/CS_MAIN	Chip select signal, Active "L"
3	RS	When RS = 0: Command. When RS = 1: Display data.
4	/WR	Write signal input <sup>,</sup> active at Low.
5	/RD	Read signal input <sup>,</sup> active at Low.
6	NC	Not connect
7	DB01	Bi-directional data bus
8	DB02	Bi-directional data bus
9	DB03	Bi-directional data bus
10	DB04	Bi-directional data bus
11	DB05	Bi-directional data bus
12	DB06	Bi-directional data bus
13	DB07	Bi-directional data bus
14	DB08	Bi-directional data bus
15	NC	Not connect
16	DB10	Bi-directional data bus
17	DB11	Bi-directional data bus
18	DB12	Bi-directional data bus
19	DB13	Bi-directional data bus
20	DB14	Bi-directional data bus
21	DB15	Bi-directional data bus
22	DB16	Bi-directional data bus
23	DB17	Bi-directional data bus
24	/LCD_RESET	Reset input pin for TFT LCD. When RESET is "L", initialization is executed.
25	NC	Not connect



Pin No	Symbol	Function
26	IM0	IM0=0,16 Bit, i80-system,DB pin assignDB17-DB10,DB8-DB1; IM0=1, 8 Bit, i80-system, DB pin assignDB17-DB10.
27	GND	System Ground.
28	X+	NC
29	Y+	NC
30	Х-	NC
31	Y-	NC
32	GND	System Ground.
33	IOVDD	Power Supply for I/O System.(2.8V)
34	VDD2	Power Supply for Analog, Digital System and Booster Circuit (2.8V)
35	LED1+	Power supply for LED Backlight Anode input
36	LED2+	Power supply for LED Backlight Anode input
37	LED3+	Power supply for LED Backlight Anode input
38	LED4+	Power supply for LED Backlight Anode input
39	LED-	Power supply for LED Backlight Cathode input



#### 2.2.1 Refer Initial Code

#### void int\_lcd()

{

write com(0x00,0x01);//Software reset write com(0x00,0x13); //normal display mode on write com(0x00,0x20); //Display inversion off write com(0x00,0x2a); //Column address set write dat(0x00,0x00); write dat(0x00,0x00); write dat(0x00,0x00); write dat(0x00,0xef); write\_com(0x00,0x2b); //Row address set write dat(0x00,0x00); write dat(0x00,0x00); write\_dat(0x00,0x01); write\_dat(0x00,0x3f); write\_com(0x00,0x2c); //Memory write write com(0x00,0x36); write dat(0x00,0x00); //Interface pixel format write\_com(0x00,0x3a); write\_dat(0x00,0x55); write com(0x00,0x55); write\_dat(0x00,0x90); //porch set write\_com(0x00,0xb2); write dat(0x00,0x0C); write\_dat(0x00,0x0C); write\_dat(0x00,0x00); write dat(0x00,0x33); write\_dat(0x00,0x33); write com(0x00,0xb7); //gate control write\_dat(0x00,0x35); write\_com(0x00,0xbb); //VCOM CONTROL write dat(0x00,0x1F); write\_com(0x00,0xc0); //Power control write\_dat(0x00,0x2c); write com(0x00,0xc2); write\_dat(0x00,0x01); write\_com(0x00,0xc3); //vrh set write dat(0x00,0x17);

//Memory data access control

//VDV and VRH command enable



write_com(0x00,0xc4	
write_dat(0x00,0x20); write_com(0x00,0xc6 write_dat(0x00,0x0f);	
write_com(0x00,0xc8	);
write_dat(0x00,0x08);	
write_com(0x00,0xca	);
write_dat(0x00,0x0f);	
write_com(0x00,0xd0	
write_dat(0x00,0xa4);	
write_dat(0x00,0xa1);	
write_com(0x00,0xfc)	; //NVM SETTIING
write_dat(0x00,0x00);	
write_dat(0x00,0x00);	
//gamma set	
write_com(0x00,0xe0	); //positive
write_dat(0x00,0xD0)	;
write_dat(0x00,0x00);	
write_dat(0x00,0x14);	
write_dat(0x00,0x15);	
write_dat(0x00,0x13);	
write_dat(0x00,0x2C)	;
write_dat(0x00,0x42);	
write_dat(0x00,0x43);	
write_dat(0x00,0x4E)	
write_dat(0x00,0x09);	
write_dat(0x00,0x16);	
write_dat(0x00,0x14);	
write_dat(0x00,0x18);	
write_dat(0x00,0x21);	
write_com(0x00,0 <mark>xe1</mark>	); //Negetive
write_dat(0x00,0 <mark>xD0)</mark>	;
write_dat(0x00,0x00);	
write_dat(0x00,0x14);	
write_dat(0x00,0x15);	
write_dat(0x00,0x13);	
write_dat(0x00,0x0B)	
write_dat(0x00,0x43);	



```
write_dat(0x00,0x55);
    write dat(0x00,0x53);
    write dat(0x00,0x0C);
    write_dat(0x00,0x17);
    write dat(0x00,0x14);
    write dat(0x00,0x23);
    write_dat(0x00,0x20);
    write com(0x00,0xe2);
    write com(0x00,0xe3);
//-----
    write com(0x00,0x11);
                             //Sleep out
    delay(120);
    write com(0x00,0x29);
                              //Display on
```

void write\_postion(uint xs,uint xe,uint ys,uint ye)

```
write com(0x00,0x2A);
{
    write dat(0x00,(xs/256));
    write_dat(0x00,(xs%256));
    write dat(0x00,(xe/256));
    write dat(0x00,(xe%256));
    write_com(0x00,0x2B);
    write dat(0x00,(ys/256));
    write dat(0x00,(ys%256));
    write_dat(0x00,(ye/256));
    write_dat(0x00,(ye%256));
    write_com(0x00,0x2c);
```

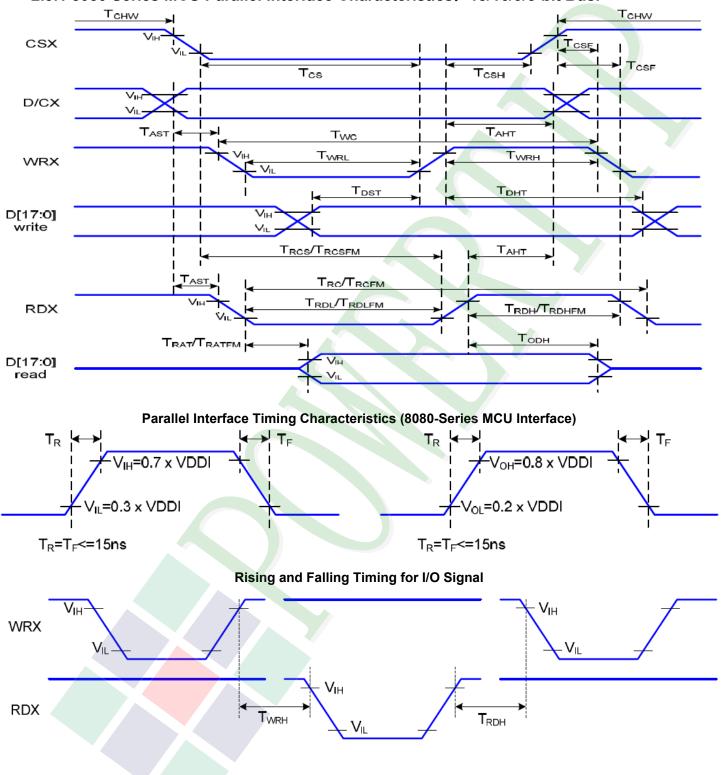
}

}



# 2.3 Timing Characteristics

## 2.3.1 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus.



#### Write-to-Read and Read-to-Write Timing

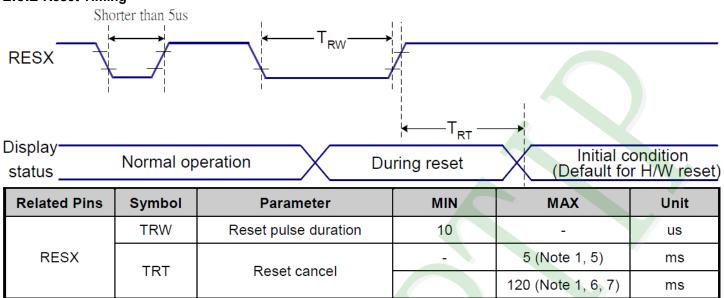
Note: The rising time and falling time (Tr, Tf) of input signal and fall time are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of IOVDD for Input signals.

POWERTIP							
Signal	Symbol	Parameter	Min	Мах	Unit	Description	
D/CX	T <sub>AST</sub>	Address setup time	0		ns		
D/CX	T <sub>AHT</sub>	Address hold time (Write/Read)	10		ns	-	
	T <sub>CHW</sub>	Chip select "H" pulse width	0		ns		
	T <sub>CS</sub>	Chip select setup time (Write)	15		ns		
CSX	T <sub>RCS</sub>	Chip select setup time (Read ID)	45		ns		
CSA	T <sub>RCSFM</sub>	Chip select setup time (Read FM)	355		ns		
	$T_{CSF}$	Chip select wait time (Write/Read)	10		ns		
	T <sub>CSH</sub>	Chip select hold time	10		ns		
	T <sub>WC</sub>	Write cycle	66		ns		
WRX	T <sub>WRH</sub>	Control pulse "H" duration	15		ns		
	T <sub>WRL</sub>	Control pulse "L" duration	15		ns		
	T <sub>RC</sub>	Read cycle (ID)	160		ns	þ.	
RDX (ID)	T <sub>RDH</sub>	Control pulse "H" duration (ID)	90		ns	When read ID data	
	T <sub>RDL</sub>	Control pulse "L" duration (ID)	45		ns		
RDX	T <sub>RCFM</sub>	Read cycle (FM)	450		ns	When read from	
(FM)	T <sub>RDHFM</sub>	Control pulse "H" duration (FM)	90		ns	frame memory	
(1 101)	T <sub>RDLFM</sub>	Control pulse "L" duration (FM)	355		ns	frame memory	
D[17:0]	T <sub>DST</sub>	Data setup time	10		ns	For CL=30pF	
	T <sub>DHT</sub>	Data hold time	10		ns		
	T <sub>RAT</sub>	Read access time (ID)		40	ns		
	T <sub>RATFM</sub>	Read access time (FM)		340	ns		
	T <sub>ODH</sub>	Output disable time	20	80	ns		

8080 Parallel Interface Characteristics



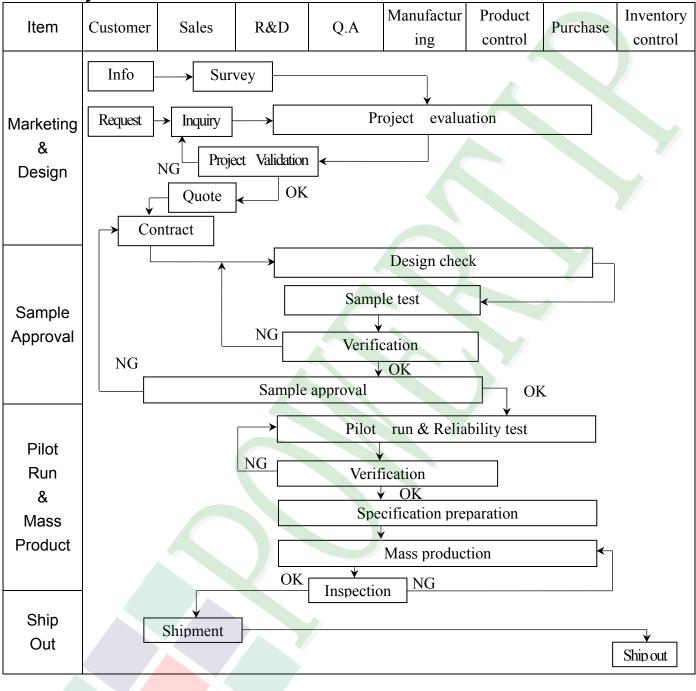
2.3.2 Reset Timing





# **3. QUALITY ASSURANCE SYSTEM**

#### 3.1 Quality Assurance Flow Chart



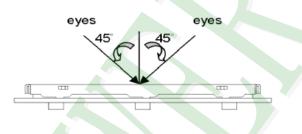


					Manufaat	Draduat		Inventory
Item	Customer	Sales	R&D	Q.A	Manufact	Product	Purchase	Inventory
					uring	control		control
Sales Service	Info Analys	→ Claim is report	[	Trackin	Failure ar			
Q.A Activity	1. ISO 900 3. Equipme 5. Standare	ent calibrat	ion	4	Process in . Education			es

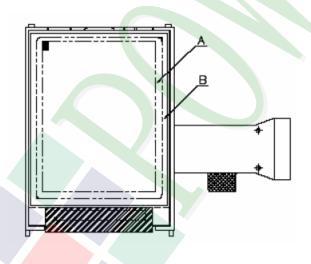
# POWERTIP

## **3.2. Inspection Specification**

- ◆Scope ∶ The document shall be applied to TFT-LCD Module for less than 3.5″ (Ver.B01).
- •Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level II.
- ◆Equipment:Gauge、MIL-STD、Powertip Tester、Sample
- ◆Defect Level:Major Defect AQL: 0.4 ; Minor Defect AQL: 1.5
- ♦OUT Going Defect Level:Sampling.
- $\clubsuit$ Standard of the product appearance test :
  - a. Manner of appearance test :
  - (1). The test best be under  $20W \times 2$  fluorescent light , and distance of view must be at 30 cm.
  - (2). The test direction is base on about around  $45^\circ$  of vertical line.



(3). Definition of area.



A area : viewing area

**B** area : Outside of viewing area

(4). Standard of inspection : (Unit : mm)



## $\clubsuit$ Specification For TFT-LCD Module Less Than 3.5":

NO	Item	Criterion			Level
		1. 1The part number is inconsistent with work order of production.			Major
01	Product condition	1.2 Mixed proc	duct types.		Major
		1.3 Assembled	in inverse direction.		Major
02	Quantity	2. 1The quantie	ty is inconsistent wit	h work order of product	ion. Major
03	Outline dimension	3. 1 Product di diagram.	mension and struct	ure must conform to stru	ucture Major
		4.1 Missing lin	e character and icon	l.	Major
		4. 2 No function or no display.			
04	Electrical Testing	4. 3 Display malfunction.			
		4. 4 LCD viewing angle defect.			
		4. 5 Current consumption exceeds product specifications.			Major
			Item	Acceptance (Q'ty)	
	Dot defect		Bright Dot	$\leq 2$	
		Dot	Dark Dot	≦ 3	
05	(Bright dot 、	Defect	Joint Dot	$\leq 2$	
05	Dark dot)		Total	$\leq 3$	Minor
	On -display	5.1 Inspection	pattern : full white blue screer	, full black , Red , Gree as.	en and
			d as dot defect if defe ce between two dot d		

(Ver.B01)



Specification For TFT-LCD Module Less Than 3.5":					
NO	Item	Crite	Criterion		
6. 1 Round type ( Non-display or display) :					
		Dimension	Acceptance	(Q'ty)	
		(diameter ÷ Φ)	A area	B area	
	Black or white dot、scratch、	$\Phi \leq 0.15$	Ignore		
	contamination	$0.15 < \Phi \leq 0.20$	2		
	Round type	$0.20 \ < \ \Phi \leq 0.30$	2	Ignore	
	→  <u>x</u>  ← <sub>↓</sub>	$\Phi > 0.30$	0		
06	Y Y	Total	3		Mino
	Φ=(x+y) / 2 Line type	6. 2 Line type( Non-display or d Dimension Length (L) Width (W)	Acceptar	nce (Q'ty) B area	
	∽ / <sup>↓</sup> w	$\begin{array}{c c} \text{Length} (L) & \text{Width} (W) \\ \hline & & \\ & & W \leq 0. \end{array}$		B area	
	→ L +-	$L \le 5.0$ 0.03 < W $\le 0.0$			
		W >0.	.05 As round type	Ignore	
		Total	3		
				1	
		Dimension (diameter ÷ Φ)	Acceptance	(Q'ty)	
		(urameter · $\Psi$ )	A area	B area	
	Polarizer	$\Phi \leq 0.20$	Ignore		
07	Bubble	$0.20 < \Phi \leq 0.50$	3	Ignovo	Mino
		$\Phi > 0.50$	0	Ignore	
		Total	3		

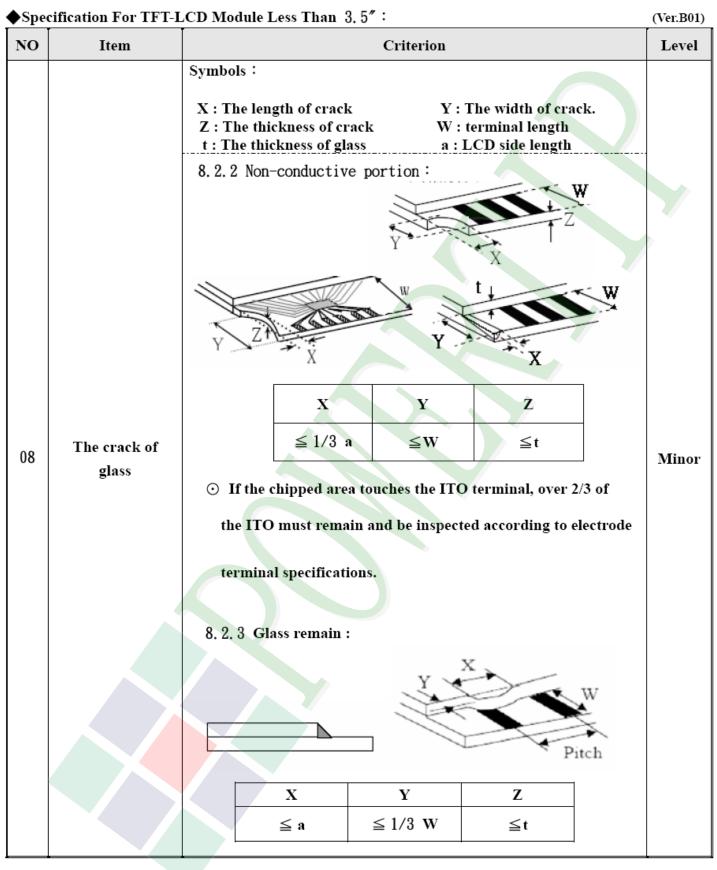


◆Specification For TFT-LCD Module Less Than 3, 5″: (V					
NO	Item	Criterion			
		Z : The thickness of crack	Y : The width of crack. W : terminal length a : LCD side length		
		8.1 General glass chip: 8.1.1 Chip on panel surface and cra	ack between panels:		
		Y Z Z	Y X X		
08	The crack of glass	SP Y [OK]	ING	Minor	
		Seal width	Y		
		X Y	Z		
		≤ a Crack can't enter viewing area	$\leq 1/2 t$		
		≤ a Crack can't exceed the half of SP width.	$1/2 t < Z \leq 2 t$		



◆Specification For TFT-LCD Module Less Than 3.5″: (Ver.B0							
NO	Item	Criterion	Level				
	Symbols :X : The length of crackY : The width of crack.Z : The thickness of crackW : terminal lengtht : The thickness of glassa : LCD side length						
		8.1.2 Corner crack :					
		X Y Z					
		$\leq 1/5 \text{ a} \qquad \begin{array}{c} \text{Crack can't enter} \\ \text{viewing area} \end{array} \qquad $					
		$\leq 1/5 \text{ a}  \begin{array}{c} \text{Crack can't exceed the} \\ \text{half of SP width.} \end{array}  1/2 \text{ t} < \text{Z}  \leq 2 \text{ t} \end{array}$					
08	The crack of glass		Minor				
		8.2 Protrusion over terminal:					
		8.2.1 Chip on electrode pad:					
		X X Y I-					
		WYY					
		X					
		X Y Z					
		Front $\leq a$ $\leq 1/2 W$ $\leq t$					
		<b>Back</b> $\leq a$ $\leq W$ $\leq 1/2 t$					







#### ◆Specification For TFT-LCD Module Less Than 3.5″:

◆Specification For TFT-LCD Module Less Than 3.5″: (V					
NO	Item	Criterion	Level		
		9. 1 Backlight can't work normally.	Major		
09	Backlight elements	9. 2 Backlight doesn't light or color is wrong.	Major		
		9. 3 Illumination source flickers when lit.	Major		
	General appearance	10. 1 Pin type 、 quantity 、 dimension must match type in structure diagram.	Major		
		10. 2 No short circuits in components on PCB or FPC .	Major		
10		10.3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major		
10		10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor		
		10. 5 The folding and peeled off in polarizer are not acceptable.	Minor		
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC ) is ≤1.5 mm.	Minor		



# **4. RELIABILITY TEST**

## 4.1 Reliability Test Condition

(Ver.B01)

4.1		ability lest condition (ver.Bui)				
NO.	TEST ITEM	TEST CC	ONDITION			
1	High Temperature Storage Test	Keep in +85°C ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.				
2	Low Temperature Storage Test	Keep in −40°C ±2°C 96 hrs Surrounding temperature, then sto	orage at normal condition 4hrs.			
3	High Temperature / High Humidity Storage Test	Keep in +60 °C / 90% R.H duration Surrounding temperature, then sto (Excluding the polarizer)				
4	Temperature Cycling Storage Test	(30mins) (5mins) ◀ 10 C	$-40^{\circ}\text{C} \rightarrow +25^{\circ}\text{C} \rightarrow +85^{\circ}\text{C} \rightarrow +25^{\circ}\text{C}$			
5	ESD Test	Air Discharge: Apply 2 KV with 5 times Discharge for each polarity +/- 1. Temperature ambiance : 15°C ~ 2. Humidity relative : 30%~60% 3. Energy Storage Capacitance(C 4. Discharge Resistance(Rd) : 330 5. Discharge, mode of operation : Single Discharge (time between s (Tolerance if the output voltage into	s+Cd) : 150pF±10% Ω±10% uccessive discharges at least 1 sec)			
6	Vibration Test (Packaged)	<ol> <li>Sine wave 10~55 Hz frequenc</li> <li>The amplitude of vibration :1.</li> <li>Each direction (X \ Y \ Z) dur</li> </ol>	5 mm			
7	Drop Test (Packaged)	Packing Weight (Kg) 0 ~ 45.4 45.4 ~ 90.8 90.8 ~ 454 Over 454 Drop Direction :%1 corner / 3 edg	122           76           61           46			
<u> </u>						



# **5. PRECAUTION RELATING PRODUCT HANDLING**

#### 5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes , please wash it off immediately by using soap and water.

## 5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully, do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth , as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands , this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is  $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM

## 5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is  $25^{\circ}C \pm 5^{\circ}C$  and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush , shake , or jolt the module.

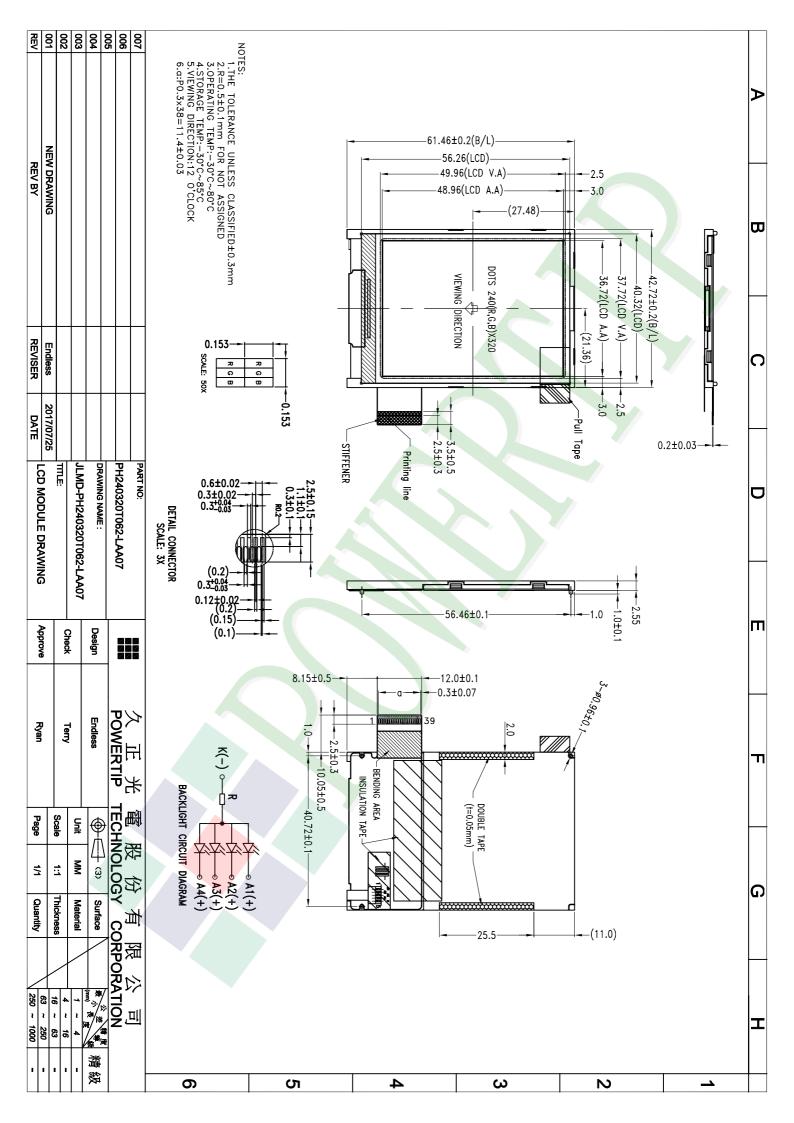
## 5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.





POWERTIP TECH. CORP.